

XCY 100 – Pick and Place Test Handler



SPECIFICATIONS:

Device types	: QFP, TSOP,SOP,PGA, BGA,PLCC, LGA 3mm X 3mm ~ 40mm X 40mm (Lead pitch : 0.4mm or more)
Test Mode	: Dual (Pitch between sockets : 80mm) Single
Index Time	: 0.5sec. (Same for ambient and high temperature, direct contact) Index time varies depending on the kind of device and socket.
Throughput	: Max.4000 pcs/hr (Ambient, dual test mode) Throughput varies depending on the kind of device and socket.
Binning	: Max. 6 bins(in the case of JEDEC tray)
Temperature	: Ambient Temperature +50°C ~ +90°C (±2°C) +90°C ~ +130°C (±3°C)
Tester Interface	: GPIB, DIO

Dimensions	: 170 x 140 x 175 cm (Excludes signal tower)
Weight	: Approx. 900kg
Power Requirements	: AC 200-240V 6KVA
Compressed Air	: 0.49MPa or more (dry and clean air)

Features :

Minimized Vibration

- Well matched mechanism and software helps to reduce the vibration of the machine
- Increases the lifespan of the socket and adaptor

Flexible Test Mode

- Soft contact design allows the IC to have minimal pressure with the socket during placement, after which the force will be adjusted to the preset pressure.
- Inaccuracy of ±0.3mm in the test socket can be compensated by the specially designed mechanism.



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